| ABSOCIATION CONNECTING<br>ELECTRODICS INDUSTRIES INCOMPACTING<br>International and Pan-Am | annockburn, Illinois.   | All rights reserved u entions. | under both    | This docume<br>level parts, t | ent is a declar<br>he declaration                                | ation of the s                    | substances<br>es all lowe | within the manual<br>r level materials | facturer listed<br>for which the | l item. N<br>manufa             | Note: if th<br>acturer ha  | e item is an ass<br>s engineering i | sembly with lower<br>responsibility. |  |
|---|---|--------------------------------|---------------|-------------------------------|--|-----------------------------------|---------------------------|--|----------------------------------|---------------------------------|----------------------------|-------------------------------------|--------------------------------------|--|
|   | IPC Web Site for Information on IPC-1752 Standard Form Type<br>http://www.ipc.org/IPC-175x Distribute |                                |               | *                             | Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Materi |                                   |                           |  |                                  | als and Mfg Information         |                            |                                     |                                      |  |
| Supplier Information  |   |                                |               |                               |  |                                   |                           |  |                                  |                                 |                            |                                     |                                      |  |
| Company name* Company unique  |   |                                | jue ID Un     |                               |  | Unique ID Authority               |                           |  |                                  | Response Date*                  |                            |                                     |                                      |  |
| onsemi  |   |                                |               |                               |  |                                   |                           |  | 2023-0                           | 2023-06-08                      |                            |                                     |                                      |  |
| Contact Name Title - Contact  |   |                                |               | ]                             | Phone - Contact*   |                                   |                           |  | Email                            | Email - Contact*                |                            |                                     |                                      |  |
| Product-Env-Stewards Product Enviro Compliance  |   |                                |               |                               | NA   |                                   |                           |  | Produ                            | Product-Env-Stewards@onsemi.com |                            |                                     |                                      |  |
| Authorized Representative* Title - Representative   |   |                                |               | ]                             | Phone - Representative*  |                                   |                           |  | Email                            | Email - Representative*         |                            |                                     |                                      |  |
| Product-Env-Stewards  | Product En  | Product Enviro Compliance      |               |                               | NA   |                                   |                           |  | Produ                            | Product-Env-Stewards@onsemi.com |                            |                                     |                                      |  |
| Requester Item Number   | Mfr Item Number   | Mfr Item Name                  | Afr Item Name |                               | Effective Da   | te Version                        | 1 I                       | Manufacturing Site                     |                                  | Weigh                           | nt*                        | UOM                                 | Unit Type                            |  |
|   | MC74LVX8051DTR<br>G   | 4LVX8051DTR2 LOG CMOS MLT      |               | N                             | 2023-06-08   |                                   | 1                         | PH1                                    |                                  | 45.4                            |                            | mg                                  | Each                                 |  |
| Manufacturing Proccess Information  |   |                                |               |                               | ·  |                                   |                           |  |                                  |                                 |                            | ·                                   |                                      |  |
| Terminal Plating / Grid Array Material  | Terminal Base   | Terminal Base Alloy            |               | 0 MSL Rating                  |  | Peak Process Body Temperature Max |                           | re Max Time at                         | Max Time at Peak Temperatu       |                                 | re Number of Reflow Cycles |                                     |                                      |  |
| Precious metal (e.g. Ag,Au, NiPdAu)<br>Sn)  | Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy Sn)  |                                | 1             |                               | 260  |                                   | С                         | 30                                     |                                  | seconds 3                       |                            |                                     |                                      |  |
| Comments  |   |                                |               |                               |  |                                   | · ·                       | ·                                      |                                  |                                 |                            |                                     |                                      |  |
| evel 1 - maximum time at peak temperature du  | ring soldering is 10  | 30 seconds                     |               |                               |  |                                   |                           |  |                                  |                                 |                            |                                     |                                      |  |
| or more information regarding material com  | osition please refer  | to page 3                      |               |                               |  |                                   |                           |  |                                  |                                 |                            |                                     |                                      |  |

| RoHS Material Composition Declaration  |   |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |
|--|---|--|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>y others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the  | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and cc<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa   | ances per the definitio  | on above  | Supplier Acceptance                             | * Accepted  |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per  | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU  |  |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |   |  |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester   | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska   | Le   |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance                  | CAS              | Exempt | Weight  | Unit of Measure |
|----------------------|--------|-----------------|----------|----------------------------|------------------|--------|---------|-----------------|
| Die                  | 2.0    | mg              | Supplier | Silicon (Si)               | 7440-21-3        |        | 2       | mg              |
| Die Attach           | 1.32   | mg              |          | Epoxy resin                | proprietary data |        | 0.132   | mg              |
|                      |        |                 | Supplier | Ethylene dimethacrylate    | 97-90-5          |        | 0.066   | mg              |
|                      |        |                 | Supplier | Silver (Ag)                | 7440-22-4        |        | 1.056   | mg              |
|                      |        |                 | Supplier | Formaldehyde Polymer       | 9003-36-5        |        | 0.066   | mg              |
| Lead Frame           | 20.76  | mg              | Supplier | Iron (Fe)                  | 7439-89-6        |        | 0.3944  | mg              |
|                      |        |                 | Supplier | Copper (Cu)                | 7440-50-8        |        | 20.3656 | mg              |
| Mold Compound-Black  | 19.0   | mg              |          | Epoxy resin                | proprietary data |        | 0.95    | mg              |
|                      |        |                 | Supplier | Phenolic Resin             | Proprietary Data |        | 0.38    | mg              |
|                      |        |                 | Supplier | Ortho Cresol Novolac Resin | 29690-82-2       |        | 0.475   | mg              |
|                      |        |                 | Supplier | Carbon Black (C)           | 1333-86-4        |        | 0.095   | mg              |
|                      |        |                 | Supplier | Fused Silica (SiO2)        | 60676-86-0       |        | 17.1    | mg              |
| Plating              | 2.12   | mg              | Supplier | Palladium (Pd)             | 7440-05-3        |        | 0.1611  | mg              |
|                      |        |                 | В        | Nickel (Ni)                | 7440-02-0        |        | 1.9292  | mg              |
|                      |        |                 | Supplier | Gold (Au)                  | 7440-57-5        |        | 0.0297  | mg              |
| Wire Bond - Au       | 0.2    | mg              | Supplier | Gold (Au)                  | 7440-57-5        |        | 0.2     | mg              |

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).